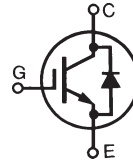
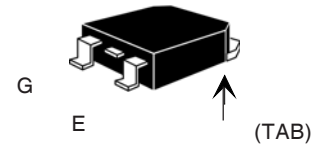
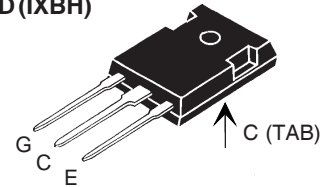


**BIMOSFET™ Monolithic  
Bipolar MOS Transistor**
**IXBH 42N170A  
IXBT 42N170A**

$$\begin{aligned} V_{CES} &= 1700 \text{ V} \\ I_{C25} &= 42 \text{ A} \\ V_{CE(sat)} &= 6.0 \text{ V} \\ t_{fi} &= 50 \text{ ns} \end{aligned}$$



Symbol	Test Conditions	Maximum Ratings
$V_{CES}$	$T_J = 25^\circ\text{C}$ to $150^\circ\text{C}$	1700 V
$V_{CGR}$	$T_J = 25^\circ\text{C}$ to $150^\circ\text{C}$ ; $R_{GE} = 1 \text{ M}\Omega$	1700 V
$V_{GES}$	Continuous	$\pm 20$ V
$V_{GEM}$	Transient	$\pm 30$ V
$I_{C25}$	$T_C = 25^\circ\text{C}$	42 A
$I_{C90}$	$T_C = 90^\circ\text{C}$	21 A
$I_{CM}$	$T_C = 25^\circ\text{C}$ , 1 ms	120 A
<b>SSOA (RBSOA)</b>	$V_{GE} = 15 \text{ V}$ , $T_{VJ} = 125^\circ\text{C}$ , $R_G = 10 \Omega$ Clamped inductive load	$I_{CM} = 90$ A $V_{CES} = 1350$ V
<b><math>T_{SC}</math> (SCSOA)</b>	$V_{GE} = 15 \text{ V}$ , $V_{CES} = 1200 \text{ V}$ , $T_J = 125^\circ\text{C}$ $R_G = 10 \Omega$ non repetitive	10 $\mu\text{s}$
$P_c$	$T_C = 25^\circ\text{C}$	350 W
$T_J$		-55 ... +150 $^\circ\text{C}$
$T_{JM}$		150 $^\circ\text{C}$
$T_{stg}$		-55 ... +150 $^\circ\text{C}$
Maximum Lead temperature for soldering 1.6 mm (0.062 in.) from case for 10 s		350 $^\circ\text{C}$
Maximum Tab temperature for soldering SMD devices for 10 s		260 $^\circ\text{C}$
$M_d$	Mounting torque (M3)	1.13/10Nm/lb.in.
<b>Weight</b>	TO-247 AD	6 g
	TO-268	4 g

**TO-268 (IXBT)**

**TO-247 AD (IXBH)**


G = Gate, E = Emitter, C = Collector, TAB = Collector

**Features**

- High Blocking Voltage
- JEDEC TO-268 surface and JEDEC TO-247 AD
- Fast switching
- High current handling capability
- MOS Gate turn-on - drive simplicity
- Molding epoxies meet UL 94 V-0 flammability classification

**Applications**

- AC motor speed control
- Uninterruptible power supplies (UPS)
- Switched-mode and resonant-mode power supplies
- Substitutes for high voltage MOSFETs

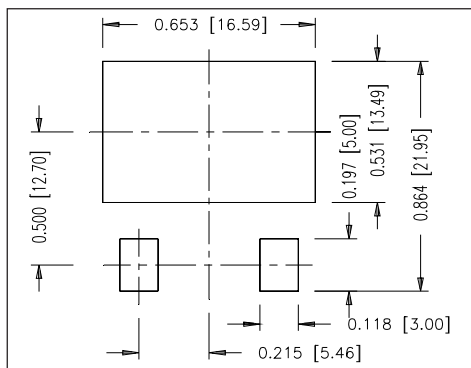
**Advantages**

- Lower conduction losses than MOSFETs
- High power density
- Suitable for surface mounting
- Easy to mount with 1 screw, (isolated mounting screw hole)

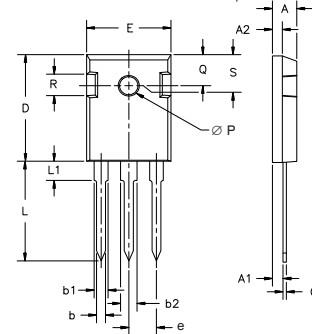
Symbol	Test Conditions	Characteristic Values ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)		
		min.	typ.	max.
$BV_{CES}$ $V_{GE(th)}$	$I_C = 250 \mu\text{A}$ , $V_{GE} = 0 \text{ V}$	1700		V
	$I_C = 750 \mu\text{A}$ , $V_{CE} = V_{GE}$	2.5		5.5 V
$I_{CES}$	$V_{CE} = 0.8 V_{CES}$ , $V_{GE} = 0 \text{ V}$			50 $\mu\text{A}$
	$T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$			1.5 mA
$I_{GES}$	$V_{CE} = 0 \text{ V}$ , $V_{GE} = \pm 20 \text{ V}$			$\pm 100$ nA
$V_{CE(sat)}$	$I_C = I_{C90}$ , $V_{GE} = 15 \text{ V}$		4.5	6.0 V
		$T_J = 125^\circ\text{C}$	5.0	V

Symbol	Test Conditions	Characteristic Values		
		$(T_J = 25^\circ\text{C}, \text{ unless otherwise specified})$		
		min.	typ.	max.
$g_{fs}$	$I_C = I_{C90}, V_{CE} = 10\text{ V}$ , Pulse test, $t \leq 300\ \mu\text{s}$ , duty cycle $\leq 2\%$	15	24	S
$C_{ies}$	$V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}, f = 1\text{ MHz}$		3700	pF
$C_{oes}$			170	pF
$C_{res}$			45	pF
$Q_g$	$I_C = I_{C90}, V_{GE} = 15\text{ V}, V_{CE} = 0.5 V_{CES}$		155	nC
$Q_{ge}$			30	nC
$Q_{gc}$			55	nC
$t_{d(on)}$	<b>Inductive load, <math>T_J = 25^\circ\text{C}</math></b> $I_C = I_{C90}, V_{GE} = 15\text{ V}$ $V_{CE} = 0.8 V_{CES}, R_G = R_{off} = 1.0\ \Omega$ Remarks: Switching times may increase for $V_{CE} \text{ (Clamp)} > 0.8 \cdot V_{CES}$ , higher $T_J$ or increased $R_G$		25	ns
$t_{ri}$			35	ns
$t_{d(off)}$			230	ns
$t_{fi}$			50	ns
$E_{off}$			2.8	mJ
$t_{d(on)}$	<b>Inductive load, <math>T_J = 125^\circ\text{C}</math></b> $I_C = I_{C90}, V_{GE} = 15\text{ V}$ $V_{CE} = 0.8 V_{CES}, R_G = R_{off} = 1.0\ \Omega$ Remarks: Switching times may increase for $V_{CE} \text{ (Clamp)} > 0.8 \cdot V_{CES}$ , higher $T_J$ or increased $R_G$		25	ns
$t_{ri}$			38	ns
$E_{on}$			5.0	mJ
$t_{d(off)}$			300	ns
$t_{fi}$			120	ns
$E_{off}$		6	mJ	
$R_{thJC}$				0.35 K/W
$R_{thCK}$	(TO-247)	0.25		K/W

Symbol	Test Conditions	Characteristic Values		
		$(T_J = 25^\circ\text{C}, \text{ unless otherwise specified})$		
		min.	typ.	max.
$V_F$	$I_F = I_{C90}, V_{GE} = 0\text{ V}$ , Pulse test, $t \leq 300\ \mu\text{s}$ , duty cycle $d \leq 2\%$			5.0 V
$I_{RM}$	$I_F = 25\text{ A}, V_{GE} = 0\text{ V}, -di_F/dt = 50\text{ A}/\mu\text{s}$		15	A
$t_{rr}$		$V_R = 100\text{ V}$		330

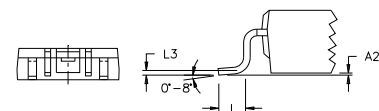
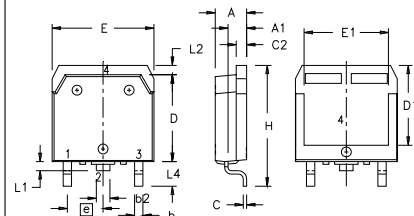


### TO-247 AD Outline



Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	4.7	5.3	.185	.209
A <sub>1</sub>	2.2	2.54	.087	.102
A <sub>2</sub>	2.2	2.6	.059	.098
b	1.0	1.4	.040	.055
b <sub>1</sub>	1.65	2.13	.065	.084
b <sub>2</sub>	2.87	3.12	.113	.123
C	.4	.8	.016	.031
D	20.80	21.46	.819	.845
E	15.75	16.26	.610	.640
e	5.20	5.72	0.205	0.225
L	19.81	20.32	.780	.800
L <sub>1</sub>		4.50		.177
∅P	3.55	3.65	.140	.144
Q	5.89	6.40	0.232	0.252
R	4.32	5.49	.170	.216
S	6.15	BSC	.242	BSC

### TO-268 Outline



SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.193	.201	4.90	5.10
A <sub>1</sub>	.106	.114	2.70	2.90
A <sub>2</sub>	.001	.010	0.02	0.25
b	.045	.057	1.15	1.45
b <sub>2</sub>	.075	.083	1.90	2.10
C	.016	.026	0.40	0.65
C <sub>2</sub>	.057	.063	1.45	1.60
D	.543	.551	13.80	14.00
D <sub>1</sub>	.488	.500	12.40	12.70
E	.624	.632	15.85	16.05
E <sub>1</sub>	.524	.535	13.30	13.60
e	.215	BSC	5.45	BSC
H	.736	.752	18.70	19.10
L	.094	.106	2.40	2.70
L <sub>1</sub>	.047	.055	1.20	1.40
L <sub>2</sub>	.039	.045	1.00	1.15
L <sub>3</sub>	.010	BSC	0.25	BSC
L <sub>4</sub>	.150	.161	3.80	4.10

IXYS reserves the right to change limits, test conditions, and dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents:

4,835,592	4,881,106	5,017,508	5,049,961	5,187,117	5,486,715	6,306,728B1
4,850,072	4,931,844	5,034,796	5,063,307	5,237,481	5,381,025	